

November 2013

FQPF19N20

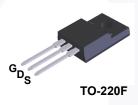
N-Channel QFET[®] MOSFET 200 V, 11.8 A, 150 m Ω

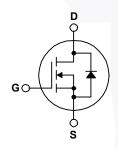
Description

This N-Channel enhancement mode power MOSFET is produced using Fairchild Semiconductor's proprietary planar stripe and DMOS technology. This advanced MOSFET technology has been especially tailored to reduce on-state resistance, and to provide superior switching performance and high avalanche energy strength. These devices are suitable for switched mode power supplies, active power factor correction (PFC), and electronic lamp ballasts.

Features

- 11.8 A, 200 V, $R_{DS(on)}$ = 150 m Ω (Max.) @ V_{GS} = 10 V, I_D = 5.9 A
- Low Gate Charge (Typ. 31 nC)
- · Low Crss (Typ. 30 pF)
- · 100% Avalanche Tested





Absolute Maximum Ratings T_C = 25°C unless otherwise noted.

Symbol	Parameter		FQPF19N20	Unit	
V _{DSS}	Drain-Source Voltage		200	V	
I _D	Drain Current - Continuous (T _C = 25°C)		11.8	Α	
	- Continuous (T _C = 100°C)		7.5	Α	
I _{DM}	Drain Current - Pulsed	(Note 1)	48	Α	
V _{GSS}	Gate-Source Voltage		± 30	V	
E _{AS}	Single Pulsed Avalanche Energy	(Note 2)	250	mJ	
I _{AR}	Avalanche Current	Current (Note 1) 11.8		Α	
E _{AR}	Repetitive Avalanche Energy	(Note 1)	5.0	mJ	
dv/dt	Peak Diode Recovery dv/dt	(Note 3)	5.5	V/ns	
P _D	Power Dissipation (T _C = 25°C)		50	W	
	- Derate above 25°C		0.4	W/°C	
T _J , T _{STG}	Operating and Storage Temperature Range		-55 to +150	°C	
T _L	Maximum Lead Temperature for Soldering, 1/8" from Case for 5 seconds		300	°C	

Thermal Characteristics

Symbol	Parameter	FQPF19N20	Unit	
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case, Max.	2.5	°C/W	
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient, Max.	62.5	°C/W	

Package Marking and Ordering Information

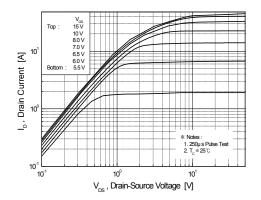
Part Number	Top Mark	Package	Packing Method	Reel Size	Tape Width	Quantity
FQPF19N20	FQPF19N20	TO-220F	Tube	N/A	N/A	50 units

Electrical Characteristics T_C = 25°C unless otherwise noted.

Symbol	Parameter	Test Conditions	Min	Тур	Max	Unit
Off Cha	aracteristics					
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} = 0 V, I _D = 250 μA	200			V
ΔBV _{DSS} / ΔT _J	Breakdown Voltage Temperature Coefficient	I _D = 250 μA, Referenced to 25°C		0.18	-	V/°C
I _{DSS} Zero Gate Voltage Drain Curre	Zana Cata Valtana Duain Courset	V _{DS} = 200 V, V _{GS} = 0 V			1	μΑ
	Zero Gate Voltage Drain Current	V _{DS} = 160 V, T _C = 125°C		1	10	μΑ
I _{GSSF}	Gate-Body Leakage Current, Forward	V _{GS} = 30 V, V _{DS} = 0 V		-	100	nA
I _{GSSR}	Gate-Body Leakage Current, Reverse	V _{GS} = -30 V, V _{DS} = 0 V		-	-100	nA
On Cha	racteristics					
V _{GS(th)}	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu\text{A}$	3.0		5.0	V
R _{DS(on)}	Static Drain-Source On-Resistance	V _{GS} = 10 V, I _D = 5.9 A		0.12	0.15	Ω
9 _{FS}	Forward Transconductance	V _{DS} = 40 V, I _D = 5.9 A		8.7		S
Dynam C _{iss}	ic Characteristics Input Capacitance	V 05 V V 0 V		1220	1600	pF
C _{oss}	Output Capacitance	$V_{DS} = 25 \text{ V}, V_{GS} = 0 \text{ V},$ f = 1.0 MHz		220	290	рF
C _{rss}	Reverse Transfer Capacitance			30	40	pF
	ing Characteristics					•
t _{d(on)}	Turn-On Delay Time	V _{DD} = 100 V, I _D = 19.4 A,		20	50	ns
t _r	Turn-On Rise Time	$R_{G} = 25 \Omega$		190	390	ns
t _{d(off)}	Turn-Off Delay Time	1.6 2022		55	120	ns
t _f	Turn-Off Fall Time	(Note 4)		80	170	ns
Qg	Total Gate Charge	V _{DS} = 160 V, I _D = 19.4 A,		31	40	nC
Q _{gs}	Gate-Source Charge	V _{GS} = 10 V	/	8.6		nC
Q _{gd}	Gate-Drain Charge	(Note 4)		13.5	-	nC
Drain-S	Source Diode Characteristics a	nd Maximum Ratings				
I _S					11.8	Α
I _{SM}	Maximum Pulsed Drain-Source Diode Forward Current				48	Α
V _{SD}	Drain-Source Diode Forward Voltage	V _{GS} = 0 V, I _S = 11.8 A			1.5	V
t _{rr}	Reverse Recovery Time	V _{GS} = 0 V, I _S = 19.4 A,		140		ns
Q _{rr}	Reverse Recovery Charge	dl _F / dt = 100 A/μs		0.69		μС

- **Notes:**1. Repetitive Rating : Pulse width limited by maximum junction temperature. 2. L = 2.7 mH, I_{AS} = 11.8 A, V_{DD} = 50 V, R_{G} = 25 Ω , starting T_{J} = 25°C. 3. $I_{SD} \le$ 19.4 A, di/dt \le 300 A/µs, $V_{DD} \le$ BV_{DSS}, starting T_{J} = 25°C. 4. Essentially independent of operating temperature.

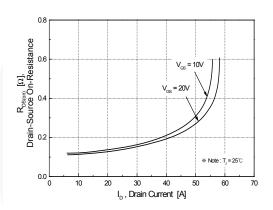
Typical Characteristics



Y 10° 25°C -55°C -

Figure 1. On-Region Characteristics

Figure 2. Transfer Characteristics



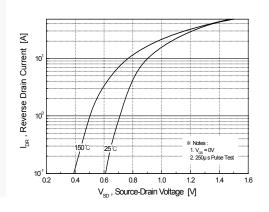
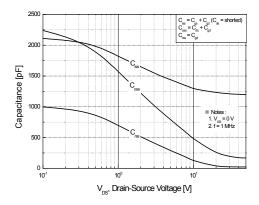


Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage

Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature



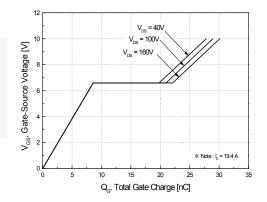
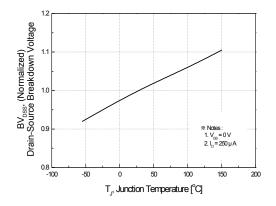


Figure 5. Capacitance Characteristics

Figure 6. Gate Charge Characteristics

Typical Characteristics (continued)



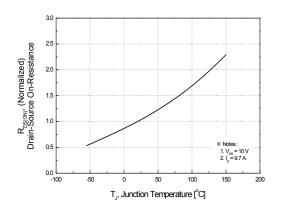
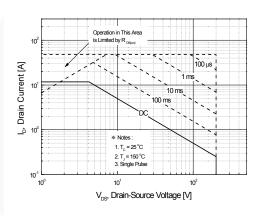


Figure 7. Breakdown Voltage Variation vs. Temperature

Figure 8. On-Resistance Variation vs. Temperature



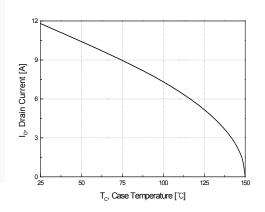


Figure 9. Maximum Safe Operating Area

Figure 10. Maximum Drain Current vs. Case Temperature

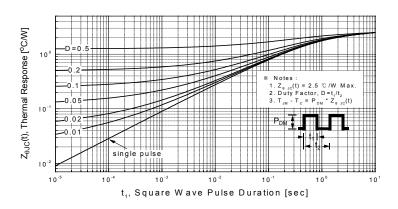


Figure 11. Transient Thermal Response Curve

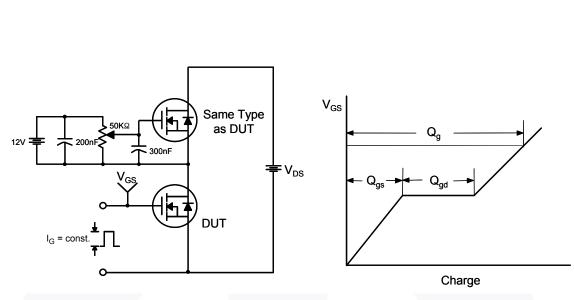


Figure 12. Gate Charge Test Circuit & Waveform

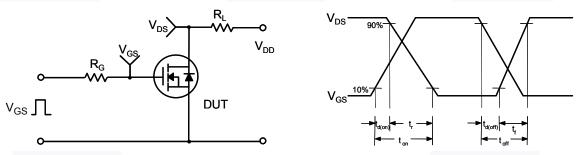


Figure 13. Resistive Switching Test Circuit & Waveforms

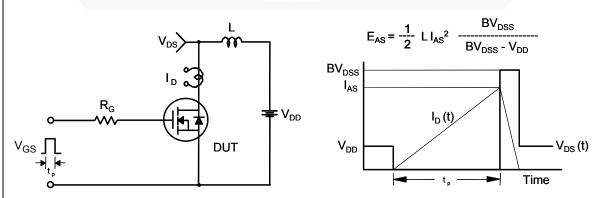
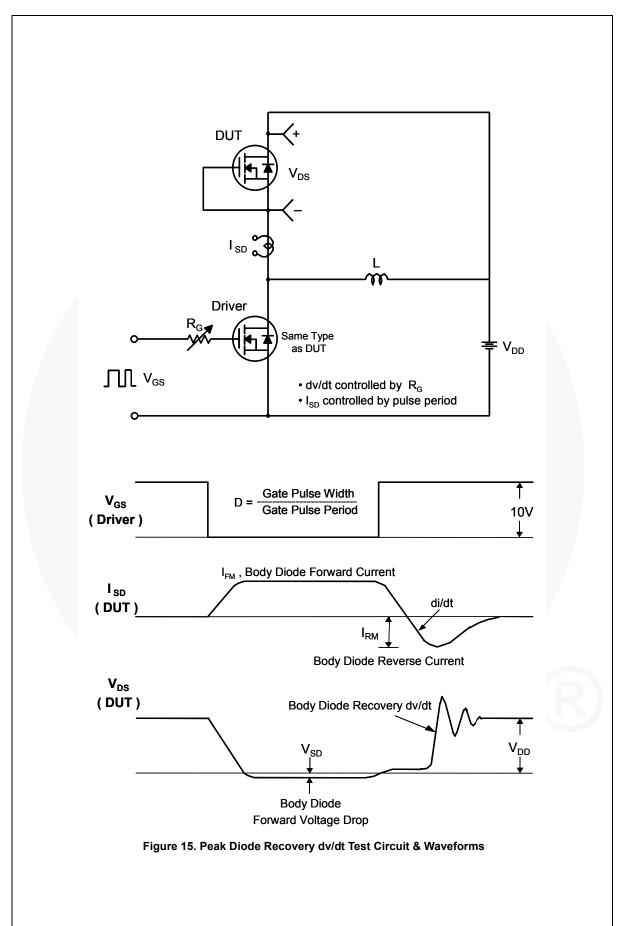


Figure 14. Unclamped Inductive Switching Test Circuit & Waveforms



Mechanical Dimensions

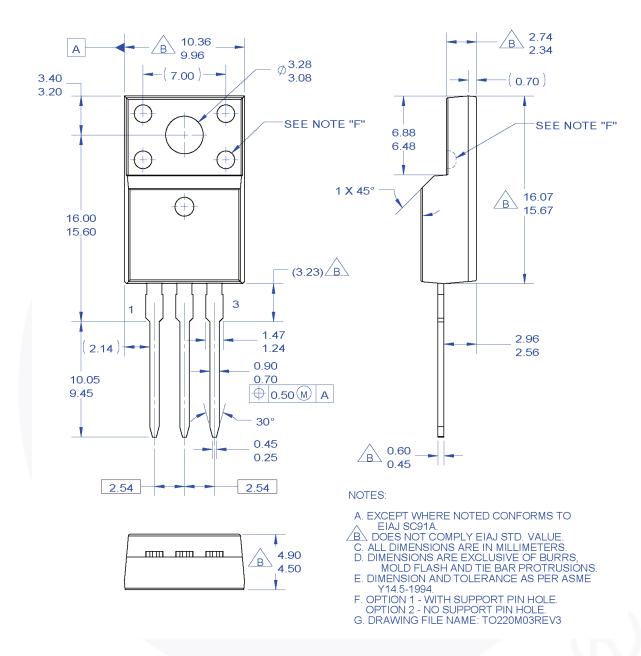


Figure 16. TO220, Molded, 3-Lead, Full Pack, EIAJ SC91, Straight Lead

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